

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Byung Joon Han</td> <td>09/17/2013</td> </tr> <tr> <td>Il Kwon Shim</td> <td>09/18/2013</td> </tr> <tr> <td>Yaojian Lin</td> <td>09/18/2013</td> </tr> <tr> <td>Pandi C. Marimuthu</td> <td>09/18/2013</td> </tr> </tbody> </table>		Name	Execution Date	Byung Joon Han	09/17/2013	Il Kwon Shim	09/18/2013	Yaojian Lin	09/18/2013	Pandi C. Marimuthu	09/18/2013
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Byung Joon Han	09/17/2013										
Il Kwon Shim	09/18/2013										
Yaojian Lin	09/18/2013										
Pandi C. Marimuthu	09/18/2013										
RECEIVING PARTY DATA											
Name:	STATS ChipPAC, Ltd.										
Street Address:	10 Ang Mo Kio Street 65										
Internal Address:	#05-17/20 Techpoint										
City:	Singapore										
State/Country:	SINGAPORE										
Postal Code:	569059										
PROPERTY NUMBERS Total: 1											
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>14036525</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	14036525						
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Application Number:	14036525										
CORRESPONDENCE DATA											
Fax Number:	4804999456										
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>											
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ATTORNEY DOCKET NUMBER:	2515.0454										
NAME OF SUBMITTER:	Robert D. Atkins										

OP \$40.00 14036525

Signature:	/Robert D. Atkins/
Date:	09/25/2013
Total Attachments: 4 source=ASSIGNMENTS#page1.tif source=ASSIGNMENTS#page2.tif source=ASSIGNMENTS#page3.tif source=ASSIGNMENTS#page4.tif	

ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, BYUNG JOON HAN of Korea, have sold, assigned, and transferred, or do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SEMICONDUCTOR DEVICE AND METHOD OF USING A STANDARDIZED CARRIER TO FORM EMBEDDED WAFER LEVEL CHIP SCALE PACKAGES, which is described, illustrated, and/or claimed in an application for patent under Attorney Docket No. 2515.0454 and U.S. Provisional Application No. 61/748,742, filed January 3, 2013, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may grant upon such application(s).

I hereby sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to application(s) for patent filed in all countries foreign to the United States, and in and to application(s) for patent filed under any and all international conventions and treaties, and in and to any patent issuing therefrom, which describe, illustrate, and claim the above-identified invention(s). I hereby also sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to all rights under any and all international conventions and treaties in respect of the above-identified invention(s). I authorize STATS ChipPAC to apply for patent in foreign countries directly in its own name, and to claim the priority of the filing date under the provisions of any and all domestic laws and international conventions and treaties.

I hereby authorize and request the government authority in the United States to issue patent(s) upon the aforesaid application, continuation, division, reissue, reexamination, extension, renewal, or substitute, to STATS ChipPAC, for the sole use and behalf of STATS ChipPAC, its successors, assigns, and legal representatives, to the full end of the term for which the patent(s) may be granted, the same as they would have been held and enjoyed by me had this assignment not been made. I authorize and request the equivalent authorities in countries foreign to the United States to issue the patents of their respective countries to and in the name of STATS ChipPAC in the same manner.

I agree that, when requested, I will, without charge to STATS ChipPAC, but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable, or convenient for securing and maintaining patents for the invention(s) in any and all countries and for vesting title thereto in STATS ChipPAC, its successors, assigns, and legal representatives or nominees.

I covenant with STATS ChipPAC, its successors, assigns, and legal representatives that the interest and property hereby conveyed is free from any prior assignment, grant, mortgage, license, or other encumbrance.

2013-09-17
Date Signed


Signature for BYUNG JOON HAN

ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, IL KWON SHIM of Singapore, have sold, assigned, and transferred, or do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SEMICONDUCTOR DEVICE AND METHOD OF USING A STANDARDIZED CARRIER TO FORM EMBEDDED WAFER LEVEL CHIP SCALE PACKAGES, which is described, illustrated, and/or claimed in an application for patent under Attorney Docket No. 2515_0454 and U.S. Provisional Application No. 61/748,742, filed January 3, 2013, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may grant upon such application(s).

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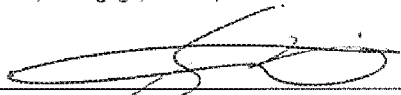
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18/09/13

Date Signed


Signature for IL KWON SHIM

ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, YAOJIAN LIN of Singapore, have sold, assigned, and transferred, or do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SEMICONDUCTOR DEVICE AND METHOD OF USING A STANDARDIZED CARRIER TO FORM EMBEDDED WAFER LEVEL CHIP SCALE PACKAGES, which is described, illustrated, and/or claimed in an application for patent under Attorney Docket No. 2515 0454 and U.S. Provisional Application No. 61/748,742, filed January 3, 2013, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may grant upon such application(s).

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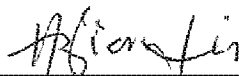
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18 Sep 2013

Date Signed



Signature for YAOJIAN LIN

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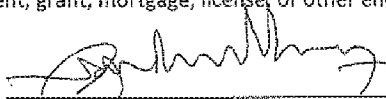
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18 Sep 2013

Date Signed



Signature for PANDI C. MARIMUTHU